NeoLink® E

A milestone in direct plating on plastics

General metal finishing | Plating on plastics | www.atotech.com

High quality, short and efficient metallization of plastics

New standard

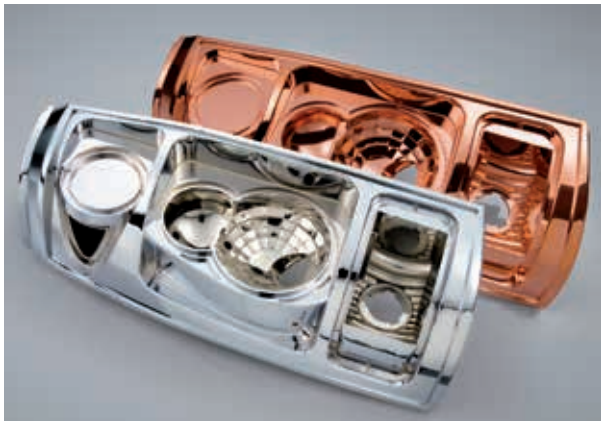
With Neolink® E, Atotech has reached a crucial new milestone in direct plating on plastics. Much shorter than conventional plating systems for plastic materials, NeoLink® E ensures fast metal deposition on ABS and ABS/PC blends with no need for electroless Ni and Ni or Cu strike.

High efficiency

NeoLink® E is designed to work with low palladium content in the activation system. The low palladium formulation of NeoLink® E activators allows for minimized drag-out costs.

Conventional plating systems usually remove tin and tin chloride after activation in the accelerator step in order to expose palladium. NeoLink® E replaces tin with copper and generates an autocatalytic growth of copper oxide crystals on the surface. That further increases the conductivity of the plastic material resulting in easier acid copper deposition as well as allowing for further palladium reduction in the activator solution.

Improved productivity, reliable production



Easily integrated into existing lines, NeoLink® E removes the need for electroless nickel, any preplate or nickel and copper strike immediately. This consequently improves productivity and the reliability of the production.

Features and benefits

- Reduced number of process and rinsing steps
- Higher conductivity before acid copper
- Less Pd in the activator working bath
- Versatile process that can be used for ABS and ABS/PC, also suitable for large parts
- Easy integration into existing electroplating equipment
- Complies with the requirements of the automotive, sanitary and fashion industries worldwide

ATOTECH

Leading plating on plastics technology – Fast and cost-effective

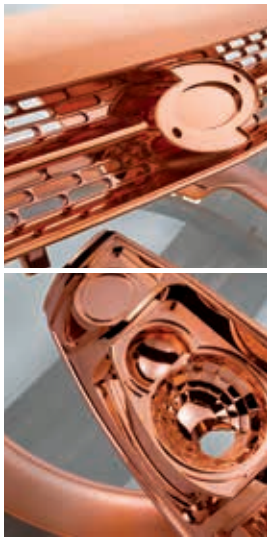


Figure 1-2:
Automotive parts plated with NeoLink® E

Shortened process sequence vs. conventional plating on plastics

Conventional plating Adhemax®	Direct plating NeoLink® E
Cleaning (optional)	**Cleaning** (optional)
Etching	**Etching**
Cr(VI) reduction	**Cr(VI) reduction**
Pre-dip	**Pre-dip**
Activation	**Activation**
Removal of Sn hydroxides	**Cu-link**
Electroless Ni	
Immersion Cu / Ni or Cu strike	
Electroplating	**Electroplating**

Electroplating

Atotech offers greatly compatible acid copper systems, especially developed for plating on plastics. Choose the right process for your application.

- Cupracid® family (dye-based)
- CuFlex® family (dye-free)

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